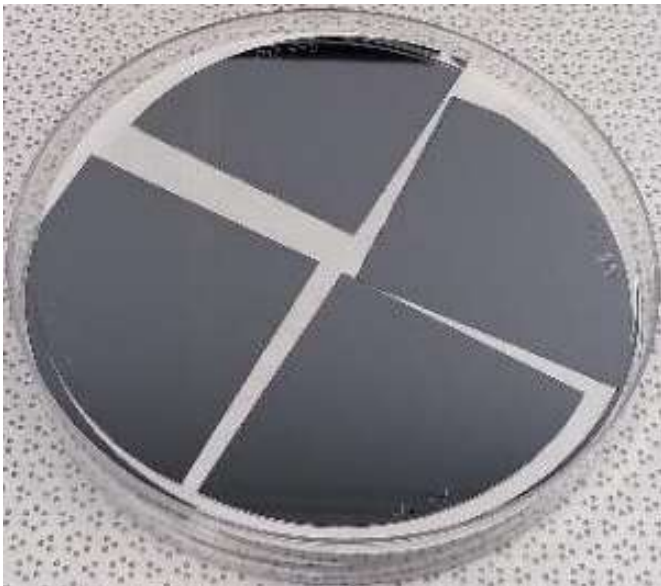


Fiji Atomic Layer Deposition (ALD) Tool

- Depositing Al_2O_3 , HfO_2 , TiO_2 , SiO_x
- Samples : Pieces – 8" Wafer
- Available Precursors: TEMA, DI H_2O ,
Ti-TDMA, Hf-TDMA
- Max Substrate Temperature : 500 °C
- DIW/Plasma Capable



AlO_x : 60nm +/- 5%

